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Practitioner's Docket No. U 13887-9

PATENT

#3 1/2/a  
6/22/24  
Sunder

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Sung-Fei WANG, et al.

Serial No.: 10/087,432

Filed: March 1, 2002

For: STACKED SEMICONDUCTOR CHIP PACKAGE

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

PRELIMINARY AMENDMENT

Please amend the above identified application as follows:

IN THE CLAIMS :

Please cancel claims 1-4:

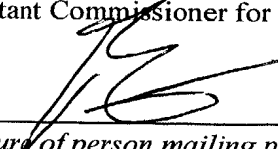
Please add new claims 5-10

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**CERTIFICATE OF MAILING (37 CFR 1.8a)**

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231

Date: April 24, 2002

  
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William R. Evans  
(type or print name of person certifying)